

## General Description

The Sanrise SRT15N075H is a low voltage power MOSFET, fabricated using advanced split gate trench technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and synchronous rectification.

The SRT15N075H break down voltage is 150V and it has a high rugged avalanche characteristics. The SRT15N075H is available in TO-220C and TO-263-2 and PDFN5\*6 packages.

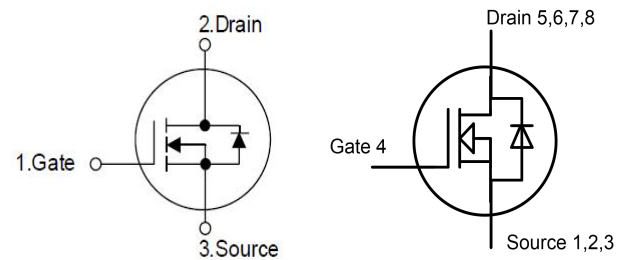
## Features

- Ultra Low  
 $R_{DS(ON\_TYP)} = 6.0m\Omega$ , TO-220C @ $V_{GS} = 10V$ .  
 $R_{DS(ON\_TYP)} = 5.9m\Omega$ , TO-263-2@ $V_{GS} = 10V$ .  
 $R_{DS(ON\_TYP)} = 5.5m\Omega$ , PDFN5\*6 @ $V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g=64.2nC$  typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved
- Non-automotive Qualified

## Application

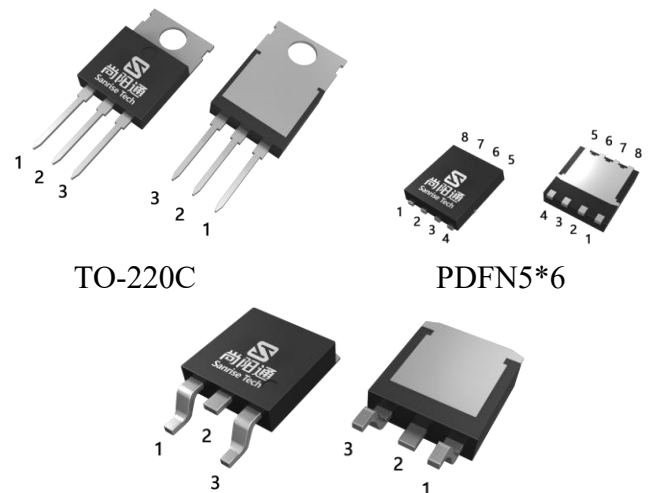
- Server/Telecom
- High Power Supply
- Solar
- UPS

## Symbol

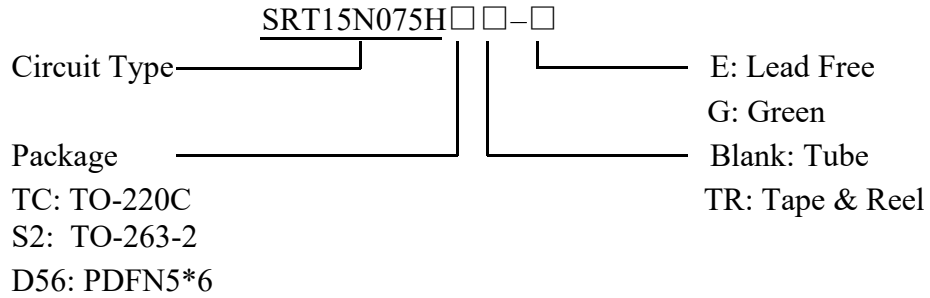


TO-220C, TO-263-2 PDFN5\*6  
 Figure 1 Symbol of SRT15N075H

## Package Type



TO-220C PDFN5\*6  
 TO-263-2  
 Figure 2 Package Type of SRT15N075H

**Ordering Information**


Package	Part Number		Marking ID		Packing Type
	Lead Free	Green	Lead Free	Green	
TO-220C	SRT15N075HTC-E	SRT15N075HTC-G	SRT15N075HTCE	SRT15N075HTCG	Tube
TO-263-2	SRT15N075HS2TR-E	SRT15N075HS2TR-G	SRT15N075HS2E	SRT15N075HS2G	Tape & Reel
PDFN5*6	SRT15N075HD56TR-E	SRT15N075HD56TR-G	SRT15N075HD56E	SRT15N075HD56G	Tape & Reel

**Absolute Maximum Ratings**

Parameter		Symbol	Rating		Unit
Drain-Source Voltage		$V_{DSS}$	150		V
Gate-Source Voltage		$V_{GSS}$	±20		V
Continuous Drain Current, Package Limited	$T_C=25^{\circ}C$	$I_D$	TO-220C	113	A
			TO-263-2	113	
			PDFN56	113	
	$T_C=100^{\circ}C$		TO-220C	80	
			TO-263-2	80	
			PDFN56	80	
Continuous Drain Current, Silicon	$T_C=25^{\circ}C$	TO-220C	113		
		TO-263-2	113		
		PDFN56	113		
Pulsed Drain Current (Note 2)		$I_{DM}$	TO-220C	452	A
			TO-263-2	452	
			PDFN56	452	
Power Dissipation ( $T_C = 25^{\circ}C$ )		$P_D$	214		W
Avalanche Destructive Energy, Single Pulse (Note 4)		$E_{AS\_Limit}$	552		mJ
Avalanche Energy, Single Pulse (Note 3)		$E_{AS}$	81		mJ
Avalanche Energy, Repetitive (Note 2)		$E_{AR}$	0.1		mJ
Avalanche Current, Repetitive (Note 2)		$I_{AR}$	22		A
Continuous Diode Forward Current		$I_S$	113		A
Diode Pulse Current		$I_{S,PULSE}$	452		A
Operating Junction Temperature		$T_J$	175		$^{\circ}C$
Storage Temperature		$T_{STG}$	-55 to 175		$^{\circ}C$
Lead Temperature (Soldering, 10 sec)		$T_{LEAD}$	260		$^{\circ}C$

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 18A$ ,  $V_{DD} = 60V$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}C$
- $I_{AS\_Limit} = 47A$ ,  $V_{DD} = 60V$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}C$

**7.5mΩ, 150V, N-Channel Power MOSFET**
**SRT15N075H**
**Thermal Resistance**

Parameter		Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	TO-220C	R <sub>thJC</sub>			0.7	°C/W
	TO-263-2				0.7	
	PDFN5*6				0.7	
Thermal Resistance, Junction-to-Ambient	TO-220C	R <sub>thJA</sub>			62	
	TO-263-2				62	
	PDFN5*6				50	

**7.5mΩ, 150V, N-Channel Power MOSFET**
**SRT15N075H**
**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	150			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=150V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	2.0	3.0	4.0	V
Static Drain-Source On-Resistance	TO-220C	$R_{DS(ON)}, V_{GS}=10V, I_D=60A$		6.0	7.5	$m\Omega$
	TO-263-2			5.9	7.5	$m\Omega$
	PDFN5*6			5.5	7.5	$m\Omega$
Gate Resistance	$R_G$	$f=1MHz, \text{Open Drain}$		1.2		$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		4.3		nF
Output Capacitance	$C_{OSS}$			1.5		nF
Reverse Transfer Capacitance	$C_{RSS}$			47		pF
Effective output capacitance, energy related <small>NOTE5</small>	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 90V$		1.4		nF
Effective output capacitance, time related <small>NOTE6</small>	$C_{O(tr)}$			1.7		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=75V, I_D=60A, R_G=1.6\Omega, V_{GS}=10V$		14		nS
Rise Time	$t_r$			5		
Turn-off Delay Time	$t_{d(off)}$			21		
Fall Time	$t_f$			5		
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	$Q_{gs}$	$V_{DD}=75V, I_D=60A, V_{GS}=0 \text{ to } 10V$		20.7		nC
Gate to Drain Charge	$Q_{gd}$			15.1		
Gate Charge Total	$Q_g$			64.2		
Gate Plateau Voltage	$V_{plateau}$			4.9		V
Gate Charge Total, sync FET	$Q_g$	$V_{DD}=0.1V, V_{GS}=0 \text{ to } 10V$		53.7		nC
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=60A$		0.87	1.1	V
Reverse Recovery Time	$t_{rr}$	$V_R=75V, I_F=60A, dI_F/dt=100A/\mu s$		28		nS
Reverse Recovery Charge	$Q_{rr}$			27		nC
Peak Reverse Recovery Current	$I_{rrm}$			1.9		A

Note:

- $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 90V
- $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 90V

**Typical Performance Characteristics**

Figure 3: Power Dissipation

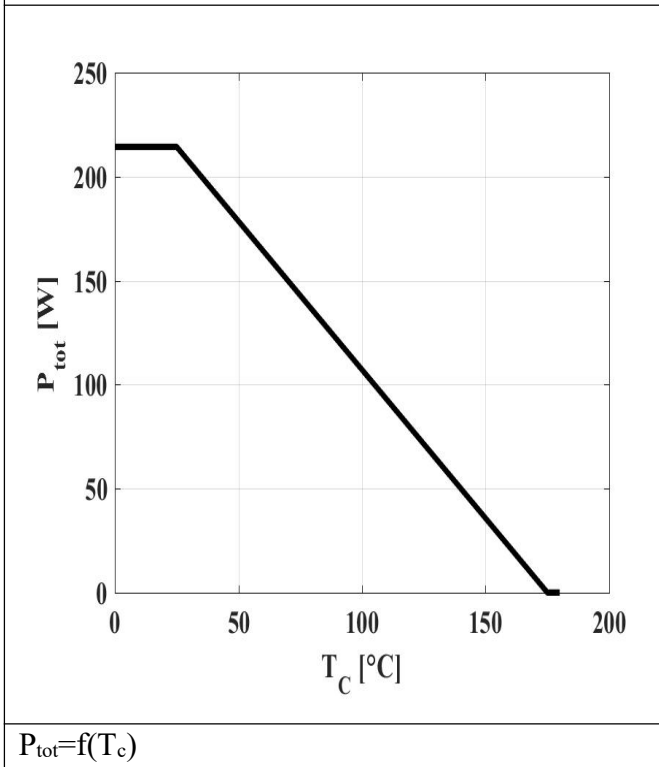


Figure 4: Max. Transient Thermal Impedance

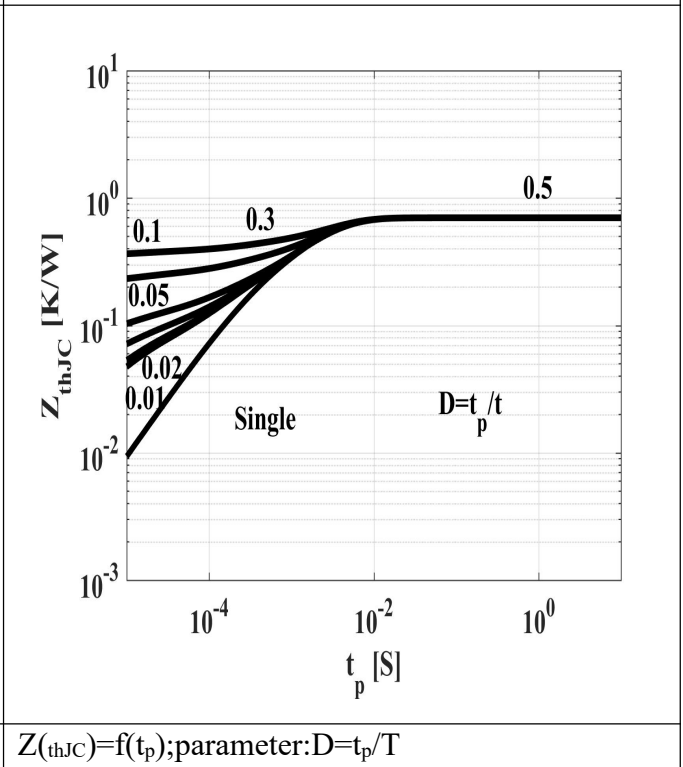


Figure 5: Drain Current

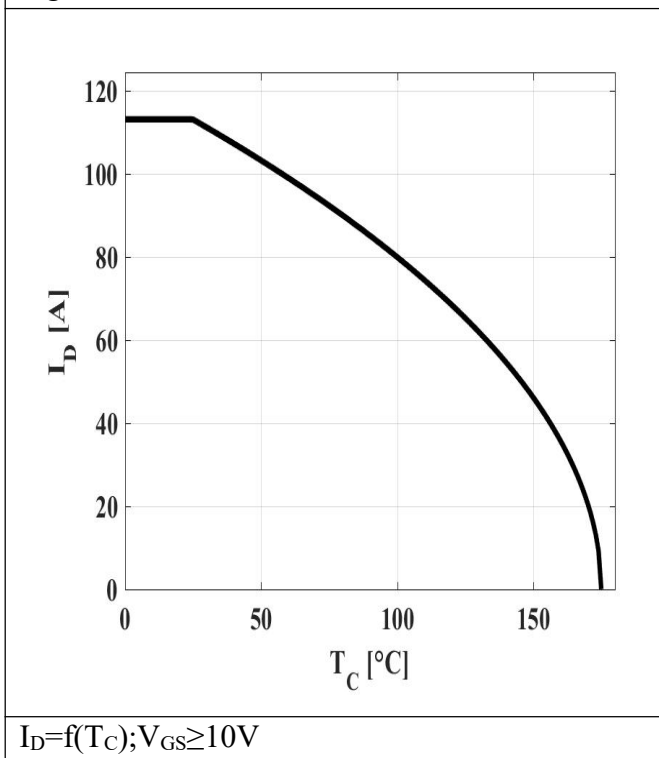
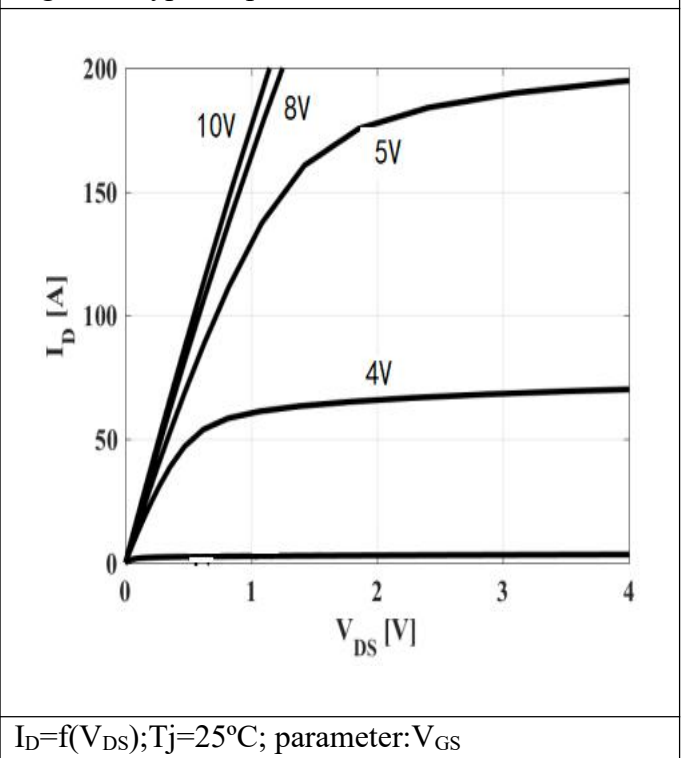
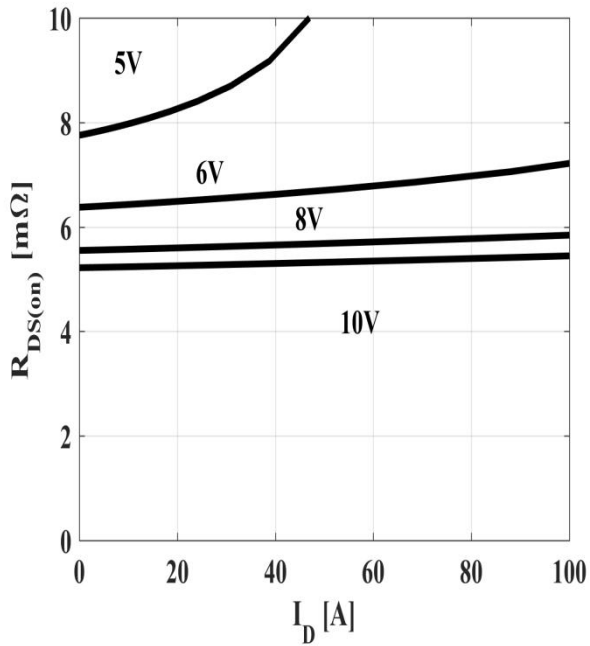
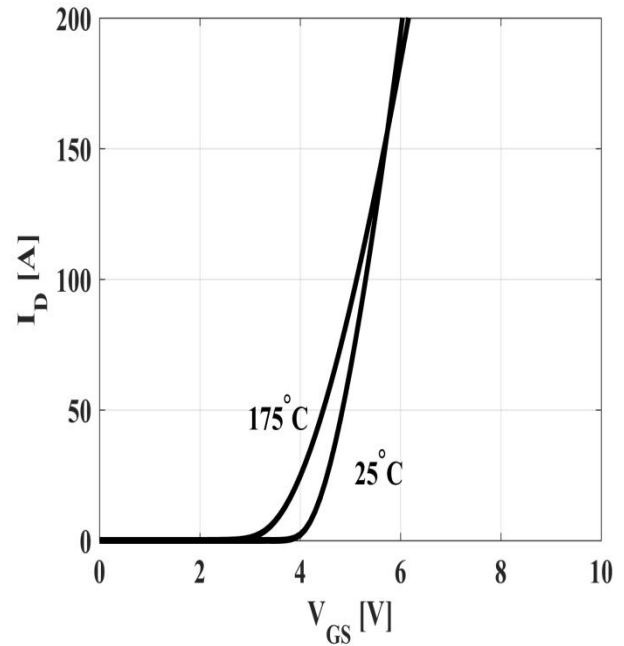
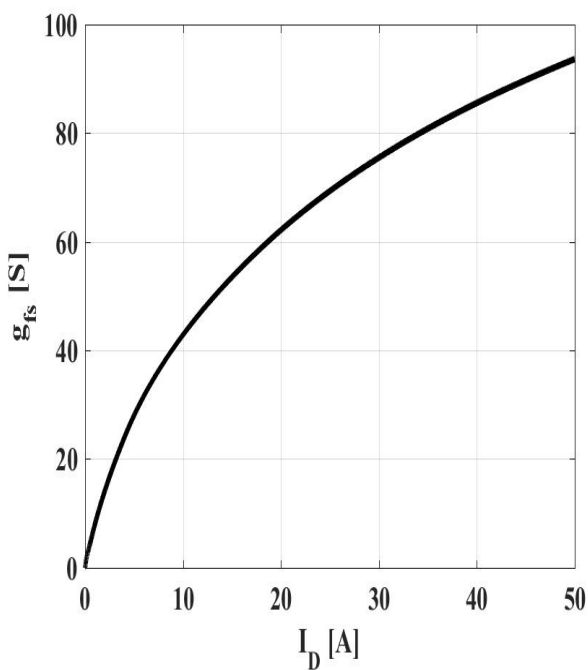
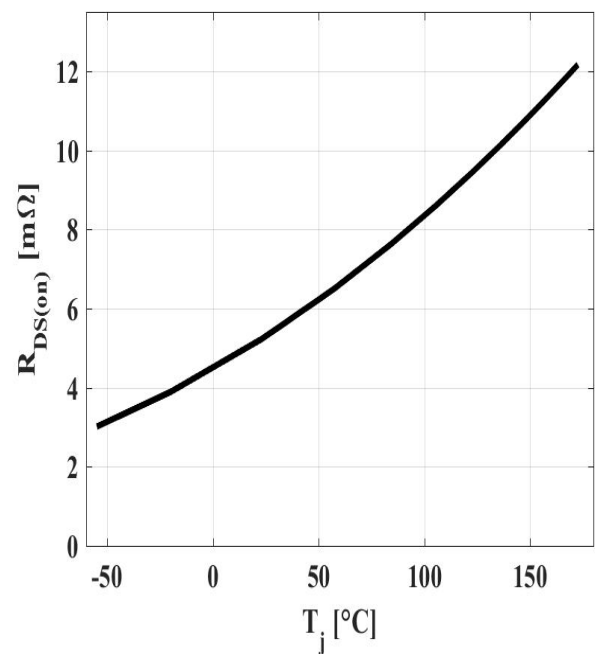
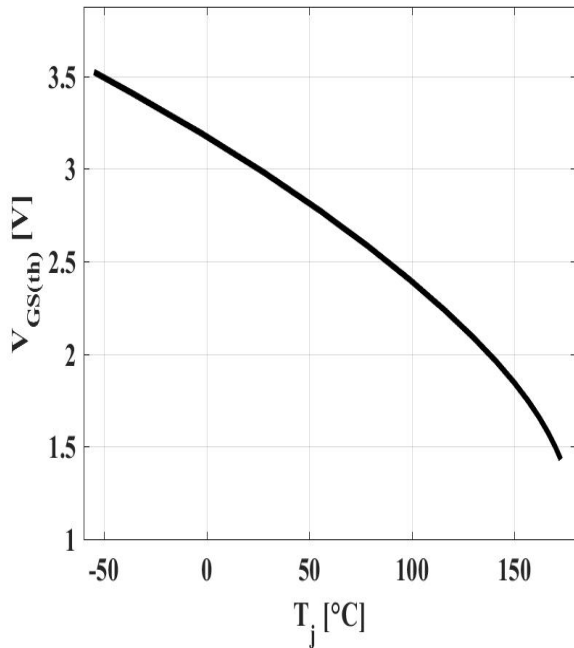


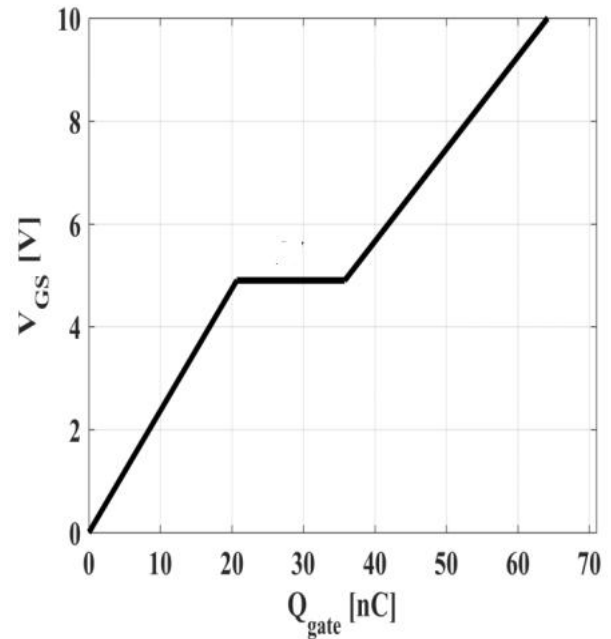
Figure 6: Typ. Output Characteristics



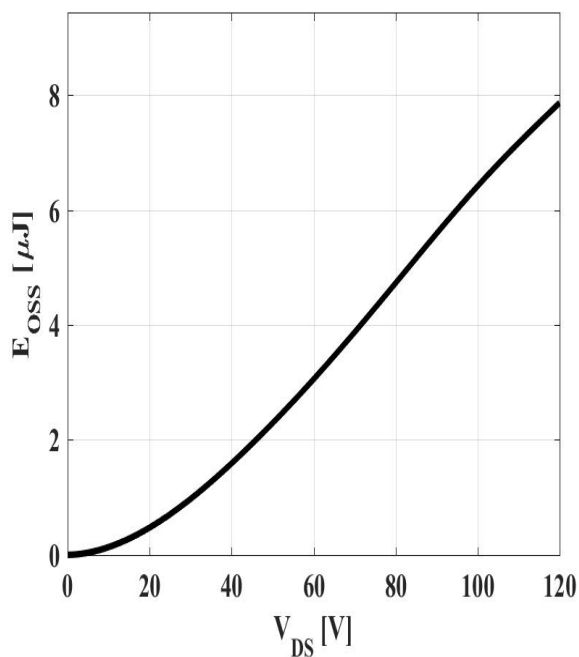
**Figure7: Typ. Drain-Source On-State Resistance**

 $R_{DS(ON)}=f(I_D); T_j=25^{\circ}C$ ; parameter:  $V_{GS}$ 
**Figure8: Typ. Transfer Characteristics**

 $I_D=f(V_{GS}); |V_{DS}|>2|I_D|R_{DS(on)max}$ ; parameter:  $T_j$ 
**Figure9: Typ. Forward Transconductance**

 $g_{fs}=f(I_D); T_j=25^{\circ}C$ 
**Figure10: Typ. Drain-Source On-State Resistance**

 $R_{DS(ON)}=f(T_j); I_D=60A; V_{GS}=10V$

**Figure 11: Typ. Gate Threshold Voltage**


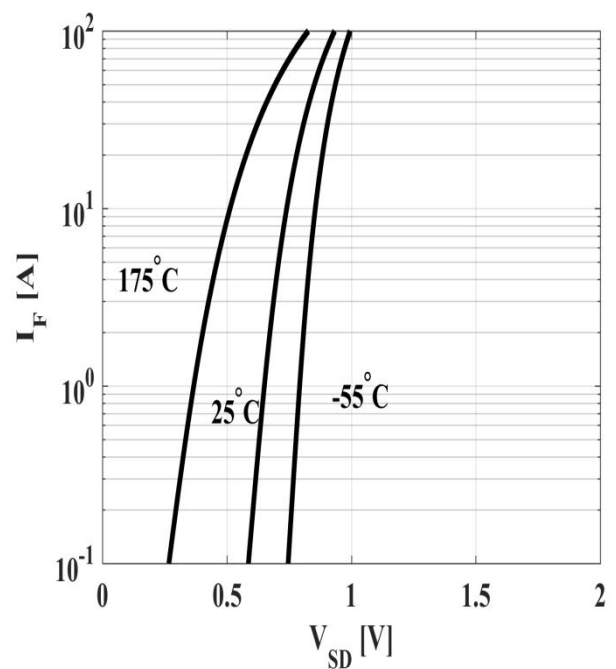
$$V_{GS(th)}=f(T_j); V_{GS}=V_{DS}; I_{DS}=250\mu A$$

**Figure 12: Typ. Gate Charge**


$$V_{GS}=f(Q_{gate}), I_D=60A \text{ pulsed}$$

**Figure 13: Coss Stored Energy**


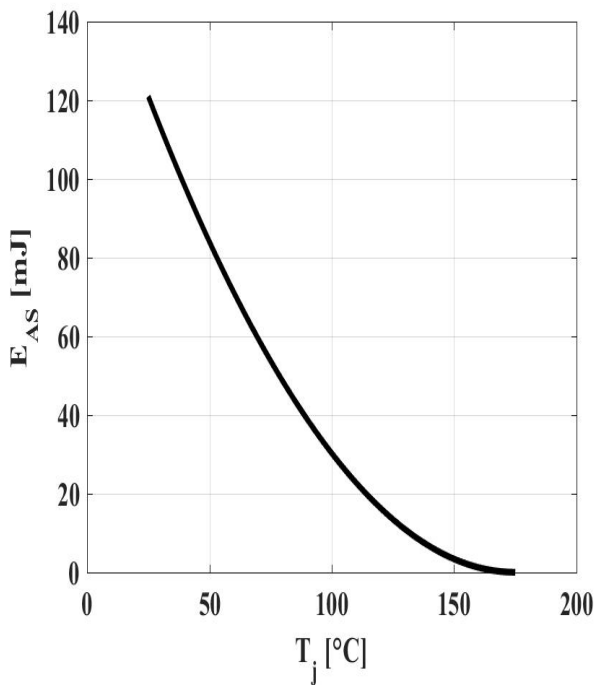
$$E_{OSS}=f(V_{DS})$$

**Figure 14: Forward Characteristics of Reverse Diode**


$$I_F=f(V_{SD}); \text{parameter: } T_j$$

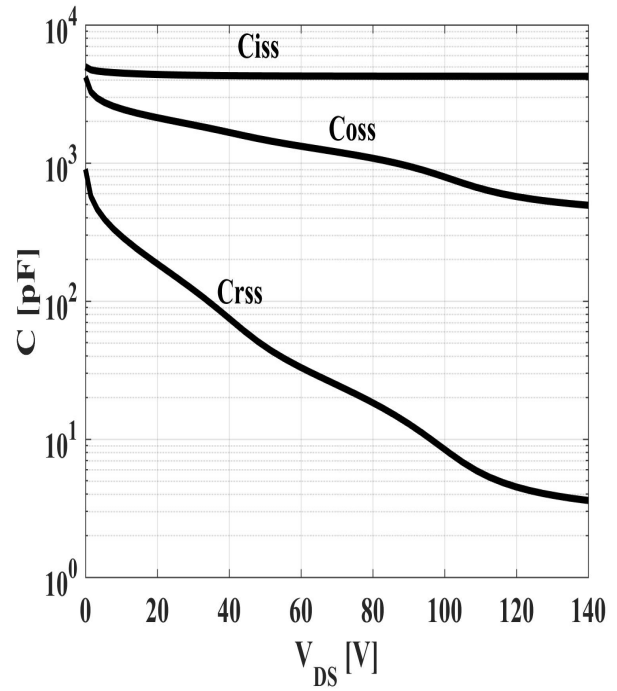


Figure 15: Avalanche Energy



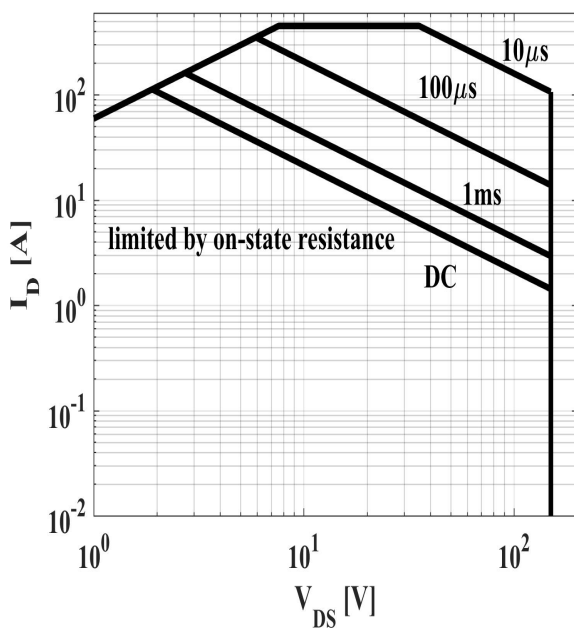
$E_{AS}=f(T_j)$ ;  $I_D=40.0A$ ;  $V_{DD}=75V$

Figure 16: Typ. Capacitances



$C=f(V_{DS})$ ;  $V_{GS}=0$ ;  $f=1MHz$

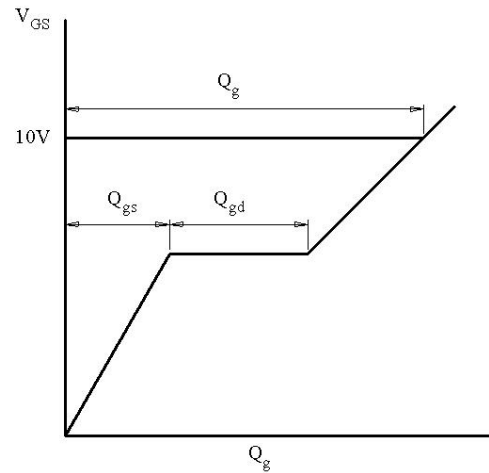
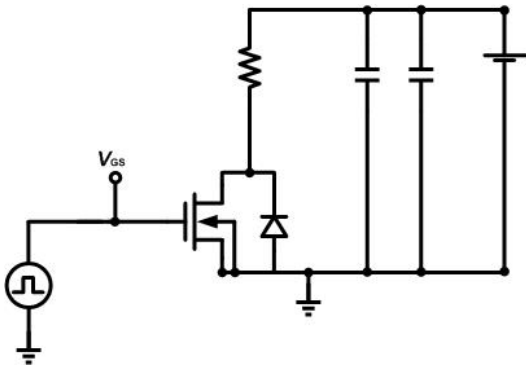
Figure 17: Safe Operating Area



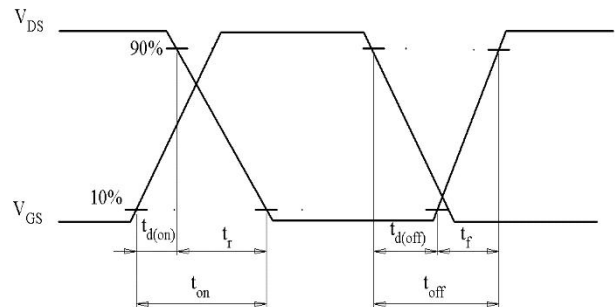
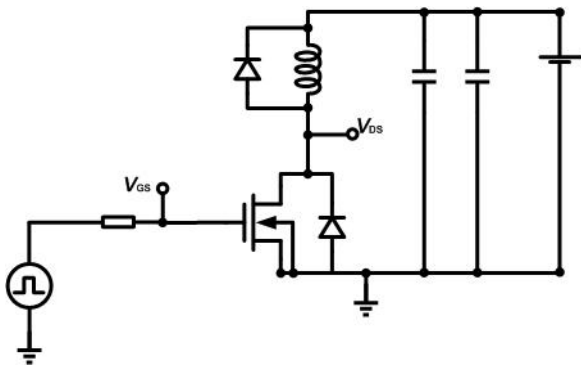
$I_D = f(V_{DS})$ ;  $T_c = 25^\circ C$ ;  $V_{GS} > 7V$ ; parameter  $t_p$

**Test Circuits**

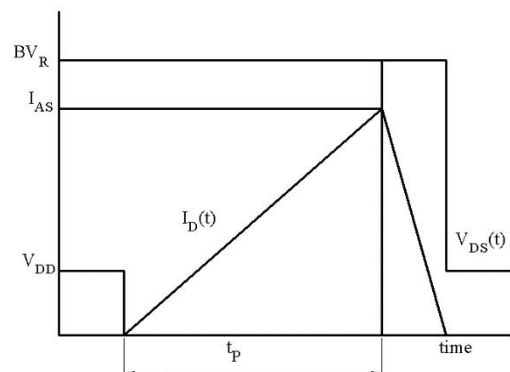
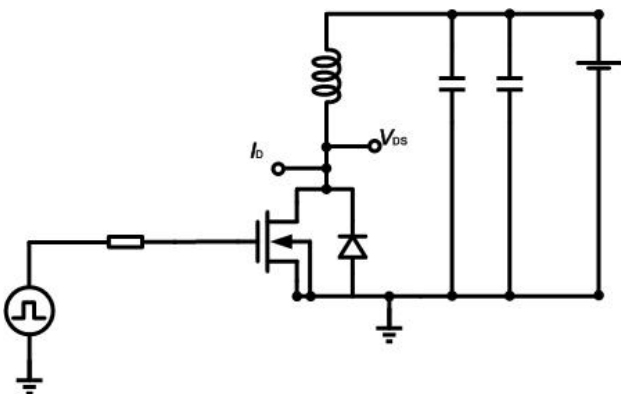
**1. Gate Charge Test Circuit & Waveform**



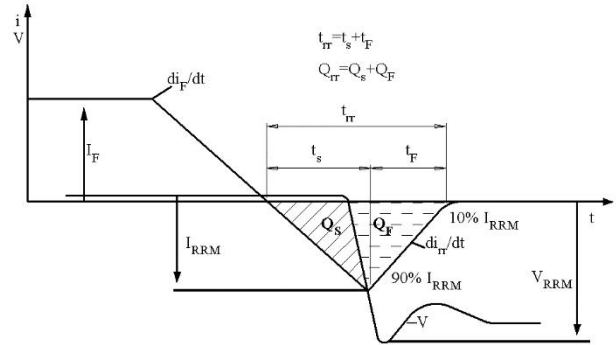
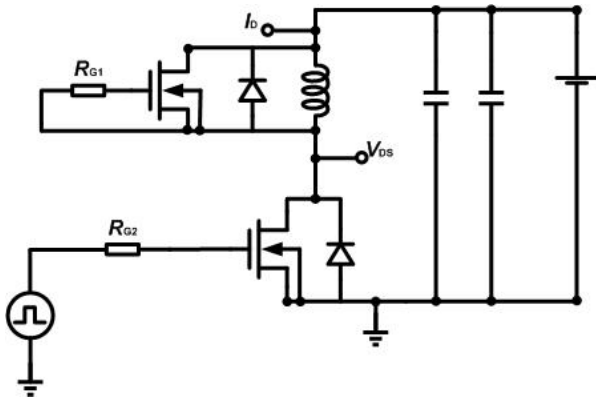
**2. Switch Time Test Circuit**

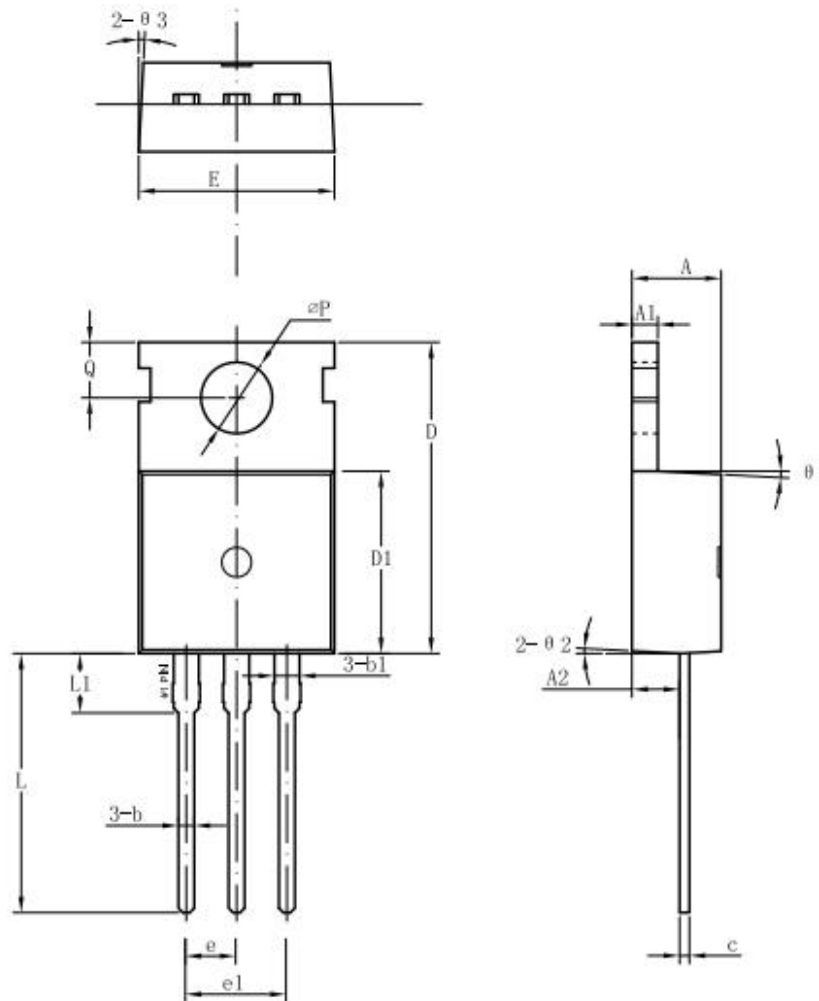


**3. Unclamped Inductive Switching Test Circuit & Waveforms**

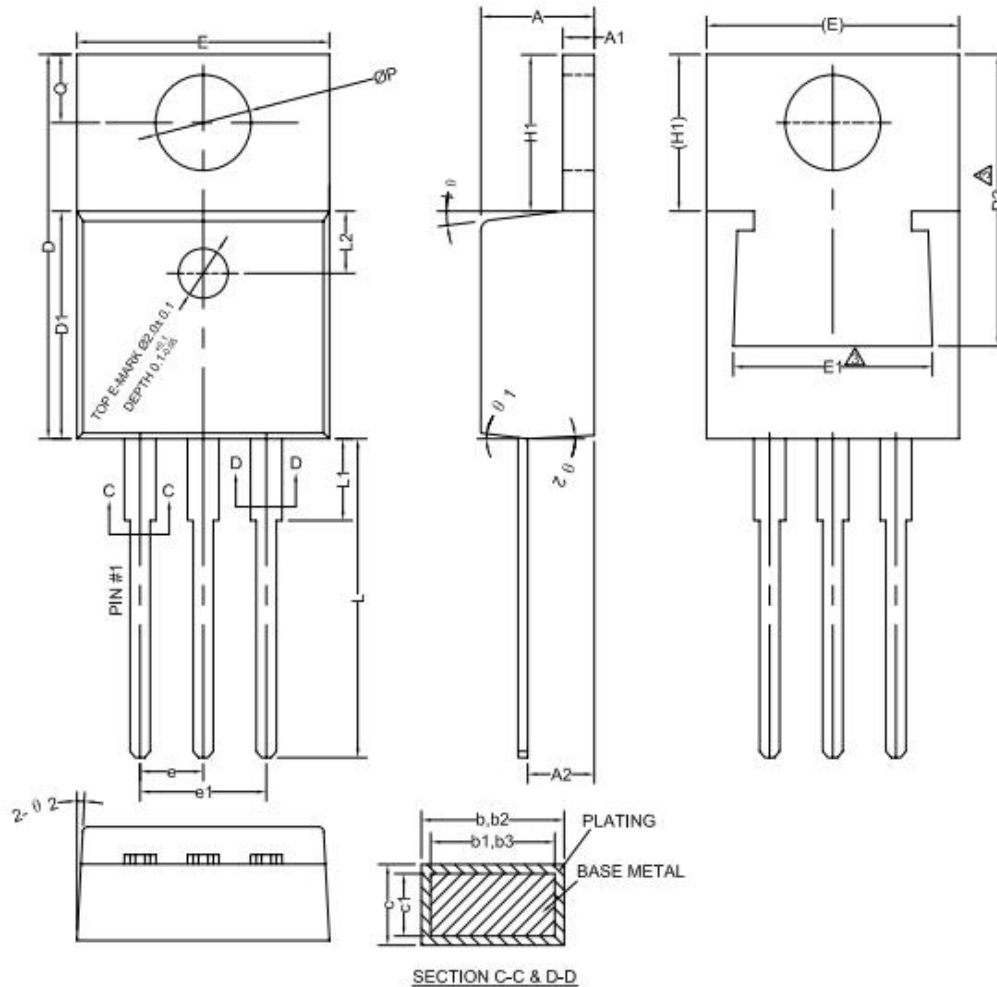


**4. Test Circuit and Waveform for Diode Characteristics**

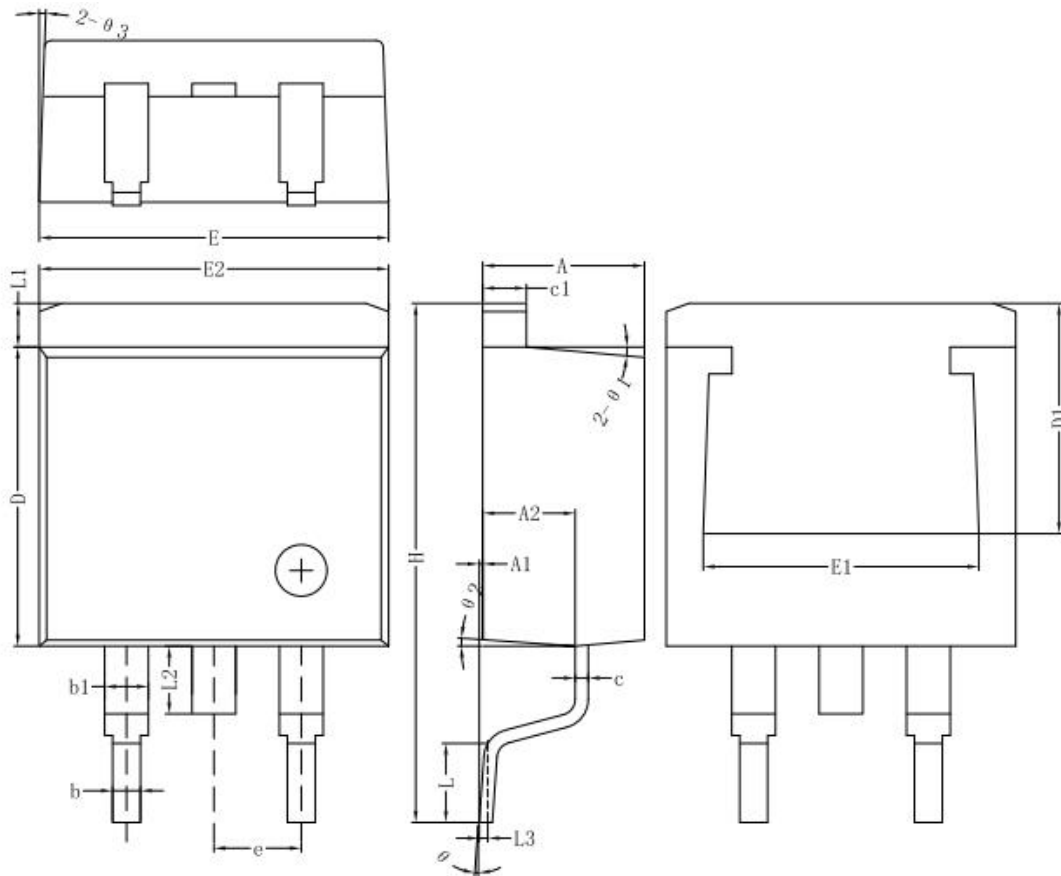


**Mechanical Dimensions**
**TO-220C(Package1)**
**Unit: mm**


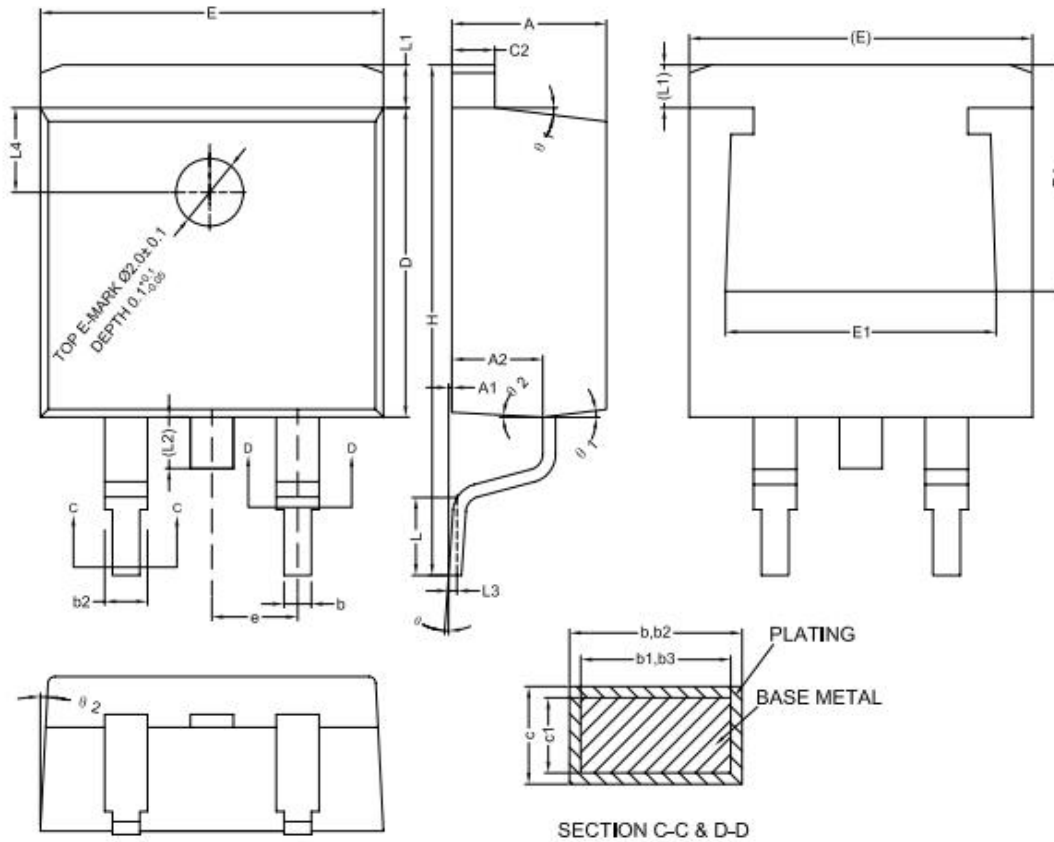
Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.30	4.50	4.70	e	-	2.54	-
A1	1.25	1.30	1.40	e1	-	5.08	-
A2	2.20	2.40	2.60	L	12.60	13.08	13.60
b	0.70	0.80	0.95	L1	-	3.00	-
b1	-	1.27	-	$\varnothing P$	3.50	3.60	3.80
c	0.40	0.50	0.65	$\varnothing 1$	-	3°	-
D	15.20	15.70	16.20	$\varnothing 2$	-	3°	-
D1	9.00	9.20	9.40	$\varnothing 3$	-	3°	-
E	9.70	10.00	10.10				

**Mechanical Dimensions**
**TO-220C(Package2)**
**Unit: mm**


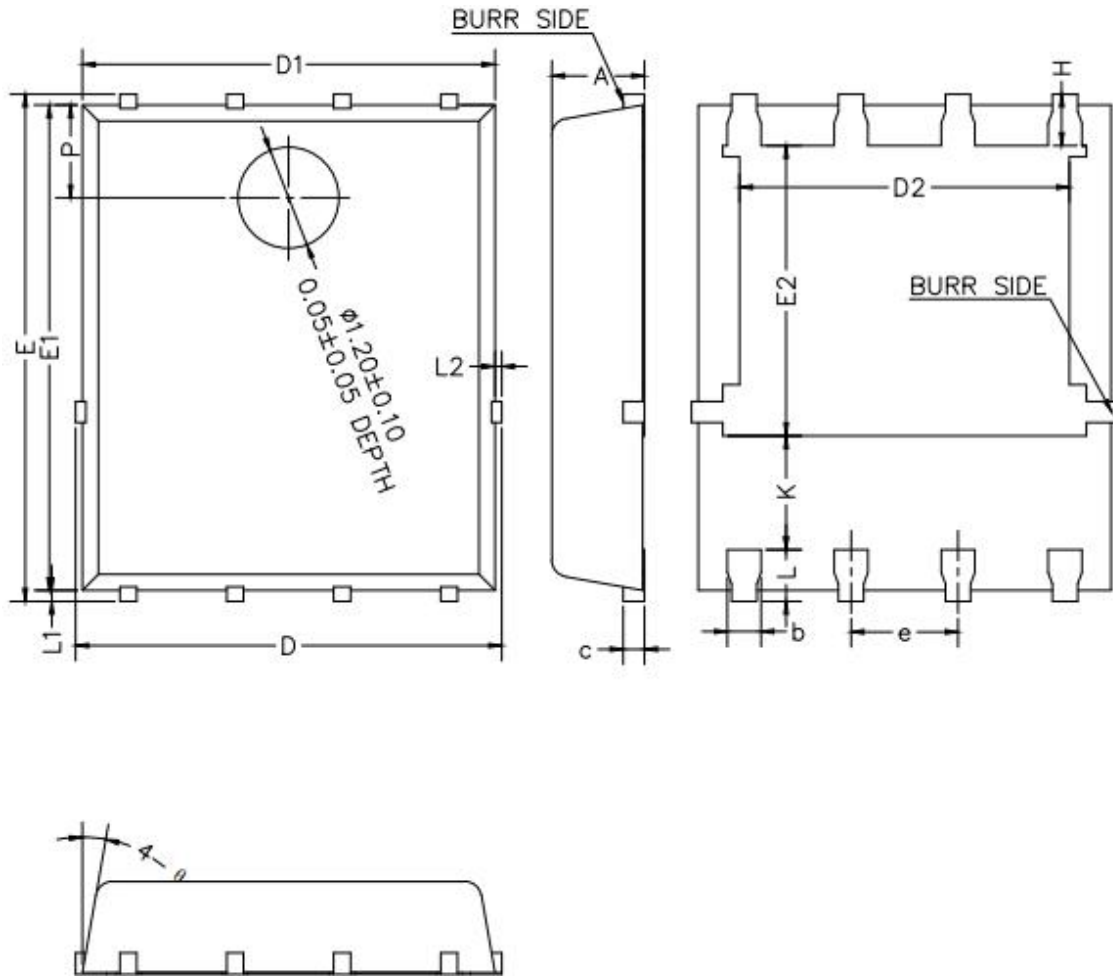
Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.40	4.57	4.70	E	9.96	10.16	10.36
A1	1.22	-	1.32	E1	6.86	-	8.89
A2	2.59	2.69	2.79	e	2.44	2.54	2.64
b	0.77	-	0.90	e1	4.98	5.08	5.18
b1	0.76	0.81	0.86	H1	6.10	6.30	6.50
b2	1.23	-	1.36	L	12.70	-	13.12
b3	1.22	1.27	1.32	L1	-	-	3.90
c	0.34	-	0.47	L2	-	2.50REF	-
c1	0.33	0.38	0.43	ΦP	3.80	3.84	3.88
D	15.15	15.45	15.75	Q	2.60	-	2.90
D1	9.05	9.15	9.25	θ 1	5°	7°	9°
D2	11.40	-	12.88	θ 2	1°	3°	5°

**Mechanical Dimensions (Continued)**
**TO-263-2(Package1)**
**Unit: mm**


Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.55	4.70	4.85	E2	9.98	10.08	10.18
A1	0.00	0.10	0.25	e	-	2.54	-
A2	2.59	2.69	2.89	H	14.70	15.10	15.50
b	0.71	0.81	0.96	L	2.00	2.30	2.70
b1	-	1.27	-	L1	1.17	1.27	1.40
c	0.36	0.38	0.61	L2	-	-	2.20
c1	1.17	1.27	1.37	L3	-	0.25BSC	-
D	8.55	8.70	8.85	⊙	0°	-	8°
D1	-	7.20	-	⊙1	-	5°	-
E	10.01	10.16	10.31	⊙2	-	4°	-
E1	-	7.8	-	⊙3	-	4°	-

**Mechanical Dimensions (Continued)**
**TO-263-2(Package2)**
**Unit: mm**


Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.40	4.57	4.70	E	10.06	10.16	10.26
A1	0.00	0.10	0.25	E1	7.80	-	8.20
A2	2.59	2.69	2.79	e	-	2.54BSC	-
b	0.77	-	0.90	H	14.70	15.10	15.50
b1	0.76	0.81	0.86	L	2.00	2.30	2.60
b2	1.23	-	1.36	L1	1.17	1.27	1.40
b3	1.22	1.27	1.32	L2	-	-	1.75
c	0.34	-	0.47	L3	-	0.25BSC	-
c1	0.33	0.38	0.43	L4	-	2.00REF	-
c2	1.22	-	1.32	Θ	0°	-	8°
D	9.05	9.15	9.25	Θ1	5°	7°	9°
D1	6.60	-	-	Θ2	1°	3°	5°

**Mechanical Dimensions**
**PDFN5\*6-8 Unit: mm**


Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	1.00	1.10	1.20	E2	3.62	-	3.82
b	0.35	0.40	0.45	H	0.38	0.48	0.58
c	0.21	0.25	0.34	K	1.10	-	-
D	-	-	5.10	L	0.51	0.61	0.71
D1	4.80	4.90	5.00	L1	0.06	0.13	0.20
D2	4.11	-	4.31	L2	-	-	0.15
e	1.17	1.27	1.37	P	1.00	1.10	1.20
E	5.90	6.00	6.10	θ	8°	10°	12°
E1	5.70	5.75	5.80				





Sanrise Technology Limited Company

<http://www.sanrise-tech.com>

#### **IMPORTANT NOTICE**

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#### **Main Site:**

##### **- Headquarter**

Shenzhen Sanrise Technology Co., LTD.

A1206, Skyworth building, No. 008, gaoxinnan 1st Road,  
Gaoxin District, Yuehai street,, Nanshan District, ShenZhen,  
P.R.China

Tel: +86-755-22953335

Fax: +86-755-22916878

##### **- Shanghai Office**

Sanrise Technology Limited Company

Rm.401, Building B, No. 666, Zhangheng Road,  
Zhangjiang Hi-Tech Park, Shanghai, P.R.China

Tel: +86-21-68825918